Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-2. (Canceled)

3. (Currently Amended) A method for fabricating a nonradiative dielectric waveguide, comprising the steps of:

forming a first conductive film on a semiconductor substrate;

forming on said first conductive film a second dielectric film whose dielectric constant is larger than that of a first dielectric film;

etching said second dielectric film to form a transmission line;

embedding said first dielectric film in an area where said second dielectric film has been etched away; and

forming a second conductive film on said first dielectric film and said second dielectric film to form a nonradiative dielectric waveguide.

4. (Currently Amended) A method for fabricating a nonradiative dielectric waveguide as claimed in claim 3, wherein ~~a MEMS circuit is fabricated into said substrate~~ said substrate includes a Micro-Electro-Mechanical System (MEMS) circuit previously formed therein.

5. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide, comprising the steps of: forming a conductive film on a substrate; forming a first sacrificial film on said conductive film; forming a groove for a transmission line passing through said first sacrificial film; embedding a dielectric into said groove formed passing through said first sacrificial film; forming a second sacrificial layer on said first sacrificial layer into which said dielectric has been embedded, and etching away said second sacrificial layer everywhere except a plurality of portions thereof; forming a conductive film in an area where said second sacrificial layer has been etched away; and etching away said first and second sacrificial layers.

6. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide as claimed in claim 5, wherein a MEMS circuit is fabricated into said substrate.

7. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide, comprising the steps of: forming a first dielectric film on a substrate; forming a groove for a transmission line to such a depth that does not pass through said first dielectric film; embedding a second dielectric, whose dielectric constant is larger than that of said first dielectric film, into said groove formed in said first dielectric film; forming another first dielectric film on said first

dielectric film and said second dielectric film; forming two grooves one spaced apart from the other by a distance smaller than the width of said second dielectric, said grooves being formed down to said substrate in such a manner as to cut off both edges of said second dielectric; and embedding a conductor into each of said two grooves.

8. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide as claimed in claim 7, wherein a MEMS circuit is fabricated into said substrate.

9-12. (Canceled)